

# Air Sampling Approaches for Engineered Nanoparticles used in the Semiconductor Industry

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QEEN II: 2nd Quantifying Exposure to Engineered Nanomaterials from  
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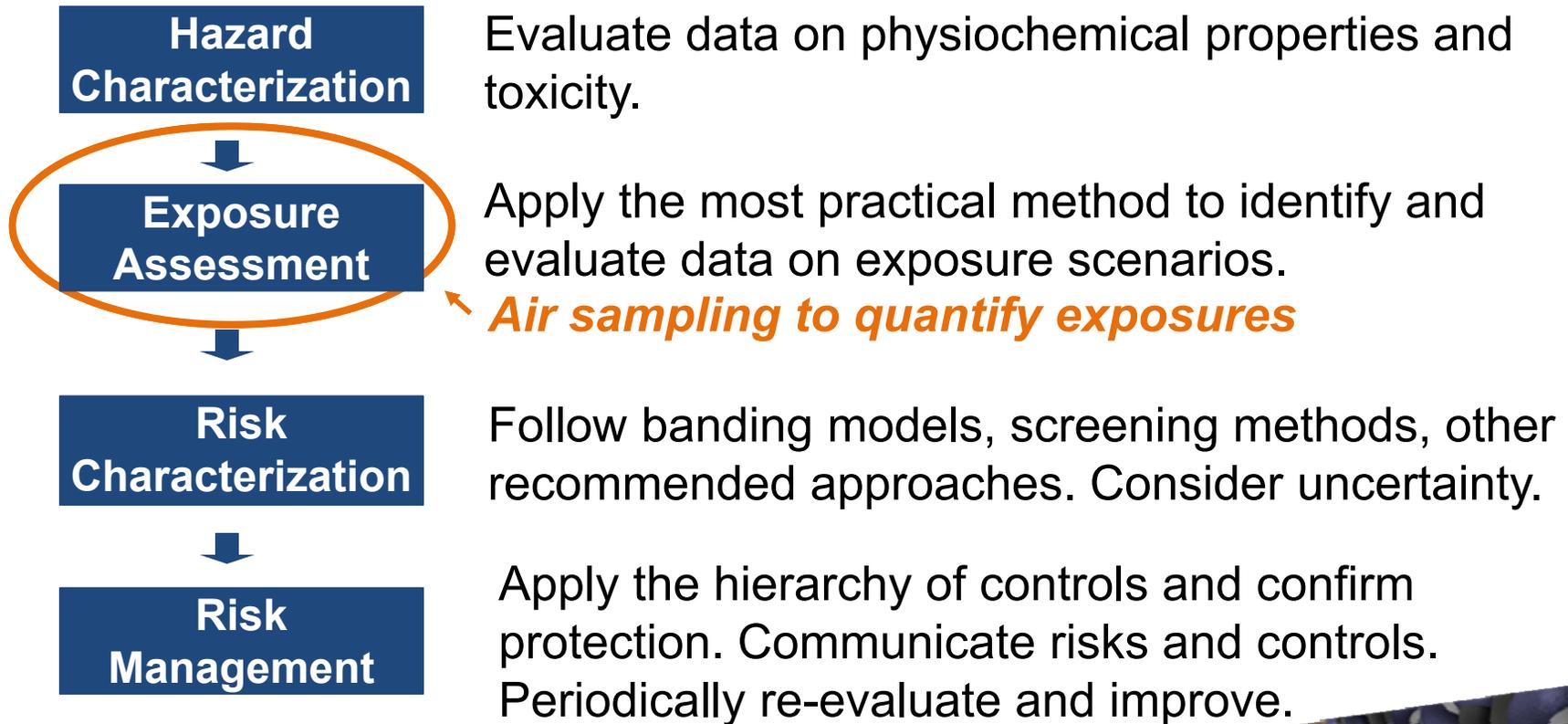
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# Workplace Exposure Assessment

Consider risks from **engineered nanomaterials (ENMs)** across the product lifecycle, applying a management system framework:

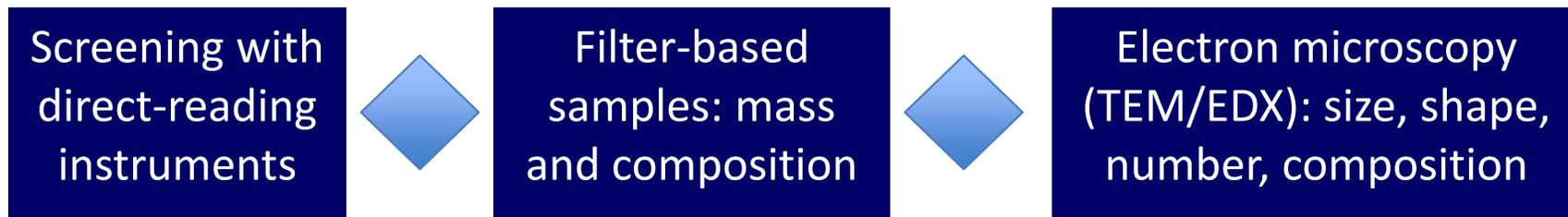


# Air Sampling Approaches

Screening level to more comprehensive approaches, depending on objectives. Common metrics include:

- Number
- Mass
- Size

*\*Particle surface area is a key factor in toxicity but not as commonly measured in workplace exposure assessments.*



# Air Sampling Challenges

## Measurement

- Commonly involves multiple methods/instruments
- Electron microscopy methods resource-intensive
- Validated methods limited
- Time-resolved devices non-specific
- Background characterization for number metric
- Differentiation from incidental ultrafine particles

## Results Interpretation

- Metrics and correlation to biological activity
- Consensus lacking on size ranges to include and data analysis methods
- Comparative values limited



Images: TSI CPC;  
TSI SMPS

# Workplace Exposure Scenario: Semiconductor Fabrication

## Chemical Mechanical Planarization (CMP)

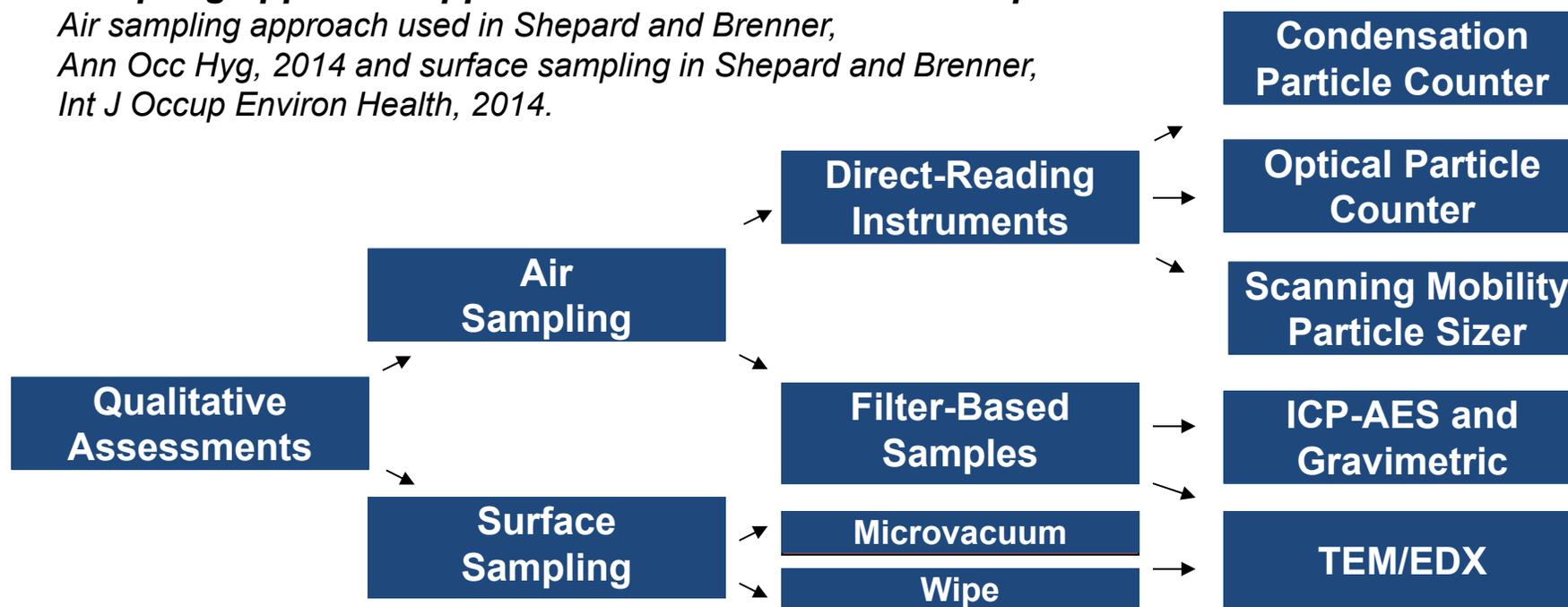
- ENMs are used as abrasives in wafer polishing processes in semiconductor fabrication
- Product formulations: typically include amorphous silica, aluminum oxide, or cerium oxide nanoparticles
- Physical forms at semiconductor fabs: slurry, powder depending on site  
*\*or embedded on pad*

Activity	Duration	Frequency
1. Operate bulk slurry delivery system	0.25-1 hr	Daily/weekly
2. Operate CMP Tool	2-8 hrs	Daily
3. Set up CMP Tool	< 0.5 hr	Daily
4. Conduct PM on CMP Tool	2-8 hrs	Monthly
5. Change pre-filter on CMP WWT system	~ 0.5 hr	Monthly
6. Clean up slurry overflow or spill	< 1 hr	As needed

# Exposure Assessment Approach used for an academic research project

**Sampling approach applied in a semiconductor workplace.**

*Air sampling approach used in Shepard and Brenner, Ann Occ Hyg, 2014 and surface sampling in Shepard and Brenner, Int J Occup Environ Health, 2014.*



ICP-AES: inductively coupled plasma - atomic emission spectroscopy.

TEM/EDX: transmission electron microscopy/energy dispersive x-ray spectroscopy.

Figure: Shepard M. © 2014

# Applicable Reference Values: Number

- Benchmark levels above background exposures for biopersistent particles 1-100 nm (IFA, 2009, 2011)
  - 20,000 p/cc for granular ENMs with density  $> 6,000 \text{ kg/m}^3$
  - 40,000 p/cc for granular ENMs with density  $< 6,000 \text{ kg/m}^3$
- 20,000 p/cc above background (BSI, 2007)

# Applicable Reference Values: Mass

- 0.3 mg/m<sup>3</sup> TWA for nanoscale titanium dioxide, for up to 10 hours (NIOSH CIB 63, 2011)
- 0.3 mg/m<sup>3</sup> TWA as an upper bound categorical guideline adjusted for other poorly soluble low toxicity (PSLT) nanoparticles (Schulte et al., *J Nanopart Res* 2010; NIOSH CIB 63, 2011)
- 0.06 x Bulk OEL for insoluble, non-fibrous ENMs (BSI, Nanotechnologies-Part 2, 2007)

# Screening Approach used by EHS practitioners

*Sampling approach currently being applied at three semiconductor manufacturing sites in the U.S.*

Considerations in selecting initial assessment approach:

- Materials of interest: ubiquitous (silica, alumina)
- Clean environments with high degree of process control
- Short duration tasks with potential for inhalation exposure
- Limited budget/resources (for TEM or multiple DRI sets)
- Limits of detection and instrument specifications
- Instruments available for rental
- No site-specific baseline data

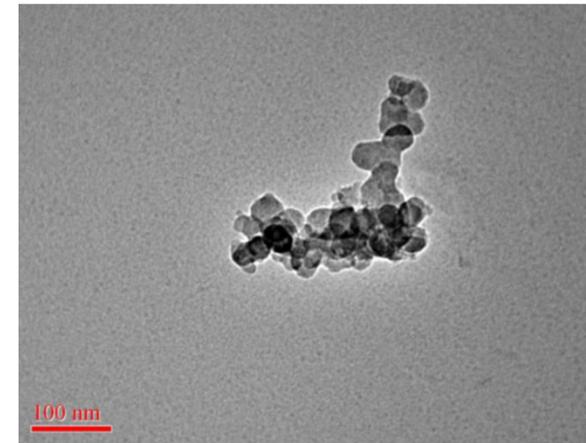
# Screening Approach used by EHS practitioners

## Screening Methods and Action Limits:

- **Number:** task measurements with condensation particle counter; probe positioned in worker breathing zone
  - 20,000 p/cc above background
  - Safety factors: measuring particles 20 to ~1000 nm and comparing to reference value for particles  $\leq 100$  nm; non-specific
- **Mass:** personal breathing zone task measurements with laser photometer with cyclone
  - 0.03 mg/m<sup>3</sup> TWA
  - Instrument lower size range: 0.1  $\mu$ m
  - Safety factors: set at 10% of NIOSH REL for nanoscale TiO<sub>2</sub>; measuring respirable particle mass; non-specific

# Progress and Future Directions

- General increase in amount and quality of data from toxicology studies
- Improved capability to collect, evaluate and interpret air sampling data with advances in:
  - Occupational exposure limits (OELs) or banding approaches
  - Method for setting OELs
  - Instrumentation/sampling devices
  - Guidelines for air sampling and analysis



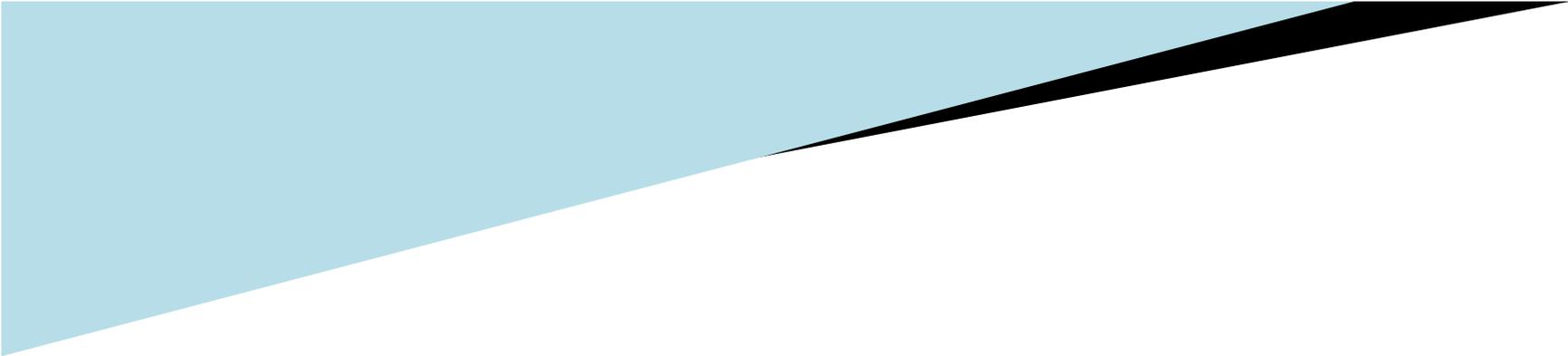
# Acknowledgements and Disclaimers

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- Exposure assessments of semiconductor applications conducted at SUNY Albany CNSE (2010-2014), with acknowledgements to Dr. Sara Brenner and group members. Funding for air and surface sampling equipment and laboratory analysis provided by the NanoHealth and Safety Center and SEMATECH.

*No information presented is intended to provide consulting advice on specific scenarios or applications; any use or adaptation of this information is at the risk of the user.*

*This presentation is intended to share experiences and observations on air sampling methods used to assess and quantify airborne concentrations and potential workplace exposures to engineered nanoparticles, and references current guidelines and standards.*



**Questions or comments:**

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